

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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**Title of
Invention**

PARTIAL WAFER BONDING AND DICING

Application Number :

10/710,880

Confirmation Number:

First Named Applicant:

Louis Hsu

Attorney Docket Number:

FIS920040114US1

Art Unit:

Examiner:

Search string:

(4962879 or 6004866 or 6010591 or 6013534 or 6538330 or 6616854).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1A	1	4962879	1990-10-16	Goesele et al	—	—	—
1A	2	6004866	1999-12-21	Nakano et al	—	—	—
1A	3	6010591	2000-01-04	Gosele	—	—	—
1A	4	6013534	2000-01-11	Mountain	—	—	—
1A	5	6538330	2003-03-25	Forbes	—	—	—
1A	6	6616854	2003-09-09	Jones et al	—	—	—

Signature

Examiner Name	Date
<i>Agarwal</i>	5/25/05

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				ATTY DOCKET NO. FIS920040114US1		APPLICATION NO. 10/710,880	
				Hsu et al.			
FILING Concurrently Herewith				GROUP ART Unknown			

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	

U.S. PATENT APPLICATION PUBLICATIONS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	

FOREIGN PATENT DOCUMENTS							
DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
					YES	NO	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)			
LA		G. Reed, "Semiconductor Packaging", Semiconductor International, September, 2003, pp. 50.	

EXAMINER Agus	DATE CONSIDERED 5/30/05
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.